Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
1752-21.1	IPC Web Site for Information on IPC-1752 Standard				Form Type Distribute	Form Type * Declaration Class *					us Materia	ials and Mfg Information				
Supplier Information																
Company name* Company unique			ique ID)			Unique ID Authority				Response Date*					
onsemi													2024-04-19			
Contact Name Tit			Title - Conta	Title - Contact			Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards		Product Envi	Product Enviro Compliance			NA					Product-Env-Stewards@onsemi.com				
Authorized Representative* Title			Title - Repre	Citle - Representative			Phone - Representative*				Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com				
	Requester Item Number	r Item Number Mfr Item Number Mfr Item Name				Effectiv	ive Date	Version	N	Manufacturin	g Site	W	eight*	UOM	Unit Type	
		AR0130CSSC00SPCA 1.2 MP 1/3 CIS 0-DRBR					2024-0	04-19		Т	TA1 264			1.22	mg	Each
Manufacturing Process Information																
	Terminal Plating / Grid Array Material Terminal Base Alloy J-9		J-STD-020 MS	L Rating	Rating Peak Proce		ss Body Temperature Max Time at Peak		Temperature Number of Reflow Cycles		es					
	Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy		4		260			С	30		seconds	3		
Comments																
For more information regarding material composition please refer to page 3																

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromir contains a RoHS restricted substance inexce encompass all such components. Supplier ce as of the date that Supplier completes this fo Company acknowledges that Supplier may l independently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated dipless of an applicable quantity limit, please intifies that it gathered the information it prome. Supplier acknowledges that Company have relied on information provided by other by others, Supplier agrees that, at a mining and the Supplier enter into a written agree esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substational substance below which, if any, RoHS exemption by desired in this form using appropriate method will rely on this certification in determining ters in completing this form, and that Supplies have provided certification between the will respect to the identified part, the Company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects to the identified part, the company's remedies for issues that arise respects the company is the co	ws of the European Union member states) of the pnce") in excess of the applicable quantity limit ide in you believe may apply. If the part is an assembly is to ensure its accuracy and that such information the compliance of its products with European Union may not have independently verified such informs regarding their contributions to the part, and tho terms and conditions of that agreement, including the provides in this formation information the Supplier provides in this formation.	entified above. If a y with lower level is true and correct on member state la nation. However, in se certifications are any warranty rigl	n homogeneous material within the part components, the declaration shall t to the best of its knowledge and belief, aws that implement the RoHS Directive. In situations where Supplier has not e at least as comprehensive as the hts and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not applicable exemptions.	contain RoHS restricted substances per	the definition above except for defined Ro	oHS exemptions, then select the corresponding	response in the R	oHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	57.0	mg		Misc.	proprietary data		0.2166	mg
			Supplier	Silicon (Si)	7440-21-3		56.2191	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5643	mg
Die Attach	2.5	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9375	mg
			Supplier	Ethylene Glycol	107-21-1		0.025	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.075	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.525	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9375	mg
Imaging Lens	60.5	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		3.025	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		3.025	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		3.025	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		3.025	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.3025	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		3.025	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		3.025	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		42.0475	mg
Lid Attach	2.6	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.8216	mg
			Supplier	Filler (SiO2)	68909-20-6		0.1352	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.8216	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.8216	mg
Mold Compound-Black	54.0	mg		Phenolic Resin	proprietary data		8.1	mg
			Supplier	Oxirane	39817-09-9		8.1	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.62	mg
			Supplier	Carbon Black (C)	1333-86-4		0.54	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		34.56	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.08	mg
Substrate and Solder Mask	87.4	mg	Supplier	Acetophenone	98-86-2		1.713	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3		19.3941	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.1449	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.1537	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2884	mg

			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2884	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.4261	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	8.74	mg
			Supplier	Copper (Cu)	7440-50-8	42.389	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	8.8624	mg
Wire Bond - Au	0.22	mg	Supplier	Gold (Au)	7440-57-5	0.22	mg